

# RH6R025BH

# Nch 150V 25A Power MOSFET

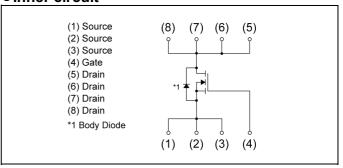
$V_{DSS}$	150V
R <sub>DS(on)</sub> (Max.)	60mΩ
I <sub>D</sub>	±25A
$P_D$	59W

# ● Outline HSMT8 (4)(3)(2)(1)

## Features

- 1) Low on resistance
- 2) High Power small mold Package (HSMT8)
- 3) Pb-free plating; RoHS compliant
- 4) Halogen Free
- 5) 100% Rg and UIS tested

# •Inner circuit



Packaging specifications

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	Packing	Embossed Tape		
	Reel size (mm)	330		
Туре	Tape width (mm)	12		
	Quantity (pcs)	3000		
	Taping code	TB1		
	Marking	R025BH		

# Application

Switching

Motor drives

DC/DC converter

# ● **Absolute maximum ratings** (T<sub>a</sub> = 25°C ,unless otherwise specified)

Parameter		Symbol	Value	Unit
Drain - Source voltage		V <sub>DSS</sub>	150	V
Continuous drain current	V <sub>GS</sub> = 10V	I <sub>D</sub> *1	±25	Α
Pulsed drain current		l <sub>DP</sub> *2	±100	Α
Gate - Source voltage		$V_{GSS}$	±20	V
Avalanche current, single pulse		I <sub>AS</sub> *3	15	Α
Avalanche energy, single pulse		E <sub>AS</sub> *3	8.9	mJ
B		P <sub>D</sub> *1	59	W
Power dissipation		P <sub>D</sub> *4	2.0	W
Junction temperature		T <sub>j</sub>	150	°C
Operating junction and storage temporary	T <sub>stg</sub>	-55 to +150	°C	

# ●Thermal resistance

Parameter	Cymphal	Values			l limit
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R <sub>thJC</sub> *1	-	-	2.1	°C/W
Thermal resistance, junction - ambient	R <sub>thJA</sub> *4	-	-	62.5	°C/W

# ●Electrical characteristics (T<sub>a</sub> = 25°C)

Doromotor	Symbol	Conditions	Values			l leit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Drain - Source breakdown voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 1mA	150	-	-	V
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_{j}}$	$\frac{\Delta V_{(BR)DSS}}{\Delta T_{i}} I_{D} = 1 \text{mA}$ referenced to 25°C		98	-	mV/°C
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 150V, V <sub>GS</sub> = 0V	-	-	5	μA
Gate - Source leakage current	I <sub>GSS</sub>	$I_{GSS}$ $V_{GS} = \pm 20V, V_{DS} = 0V$		1	±500	nA
Gate threshold voltage	$V_{GS(th)}$	$V_{GS(th)}$ $V_{DS} = V_{GS}$ , $I_D = 1mA$		-	4.0	V
Gate threshold voltage temperature coefficient	$\frac{\DeltaV_{GS(th)}}{\DeltaT_j}$	I <sub>D</sub> = 1mA referenced to 25°C	-	-5.7	-	mV/°C
Static drain - source	D *5	V <sub>GS</sub> = 10V, I <sub>D</sub> = 25A	-	46	60	C
on - state resistance	R <sub>DS(on)</sub> *5	V <sub>GS</sub> = 6V, I <sub>D</sub> = 12.5A	-	49	73	mΩ
Gate resistance	$R_{G}$	-	-	1.6	-	Ω
Forward Transfer Admittance	Y <sub>fs</sub>  *5	V <sub>DS</sub> = 5V, I <sub>D</sub> = 12.5A	11	-	-	S

<sup>\*1</sup>  $T_c$ =25°C, Limited only by maximum temperature allowed.



<sup>\*2</sup> Pw≤ 10µs , Duty cycle≤ 1%

<sup>\*3</sup> L  $\simeq$  0.05mH,  $V_{DD}$  = 75V,  $R_G$  = 25 $\Omega$ , Starting  $T_j$  = 25 $^{\circ}$ C Fig.3-1,3-2

<sup>\*4</sup> Mounted on a Cu board (40×40×0.8mm)

<sup>\*5</sup> Pulsed

# ● Electrical characteristics (T<sub>a</sub> = 25°C)

Davamatav	Cymahal	Conditions	Values			Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V	-	1010	-	
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 75V	-	95	-	pF
Reverse transfer capacitance	C <sub>rss</sub>	f = 1MHz	-	12	-	
Turn - on delay time	t <sub>d(on)</sub> *5	V <sub>DD</sub> ≈ 75V,V <sub>GS</sub> = 10V	1	18	1	
Rise time	<b>t</b> r*5	I <sub>D</sub> = 12.5A	1	12	ı	no
Turn - off delay time	t <sub>d(off)</sub> *5	$R_L \simeq 6\Omega$	-	36	-	ns
Fall time	<b>t</b> <sub>f</sub> *5	$R_G = 10\Omega$	-	15	-	

# • Gate charge characteristics $(T_a = 25^{\circ}C)$

Daramatar	Cymahal	Conditions		Values			1.1:4
Parameter	Symbol			Min.	Тур.	Max.	Unit
Total gate charge	O *5		V <sub>GS</sub> = 10V	-	16.7	-	
Total gate charge	$Q_g$	$Q_g^{*5}$ $V_{DD} \simeq 75V$		-	11.0	-	
Gate - Source charge	Q <sub>gs</sub> *5	I <sub>D</sub> = 25A	V <sub>GS</sub> = 6V	-	3.7	-	nC
Gate - Drain charge	Q <sub>gd</sub> *5			-	4.4	-	

# ● Body diode electrical characteristics (Source-Drain) (T<sub>a</sub> = 25°C)

Parameter	Cumbal	Conditions		Unit		
raiametei	Symbol	Conditions	Min.	Тур.	Max.	Offic
Continuous forward current	I <sub>S</sub> *1		-	-	25	Α
Pulse forward current	I <sub>SP</sub> *2		-	-	100	Α
Forward voltage	V <sub>SD</sub> *5	$V_{GS} = 0V, I_{S} = 25A$	-	-	1.2	V
Reverse recovery time	t <sub>rr</sub> *5	I <sub>S</sub> = 25A, V <sub>GS</sub> =0V	-	115	-	ns
Reverse recovery charge	Q <sub>rr</sub> *5	di/dt = 100A/μs	-	375	-	nC

Fig.1 Power Dissipation Derating Curve

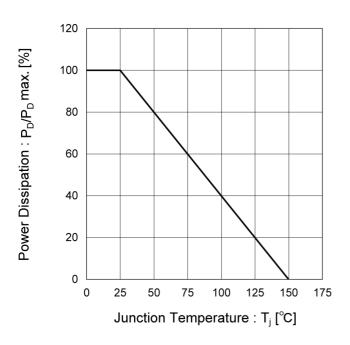
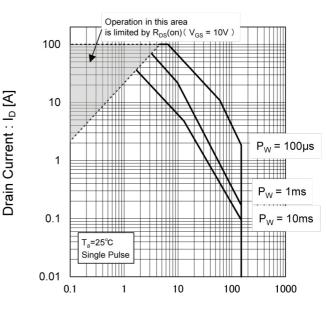


Fig.2 Maximum Safe Operating Area



Drain - Source Voltage : V<sub>DS</sub> [V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

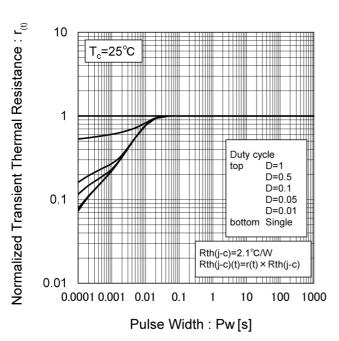


Fig.4 Single Pulse Maximum Power Dissipation

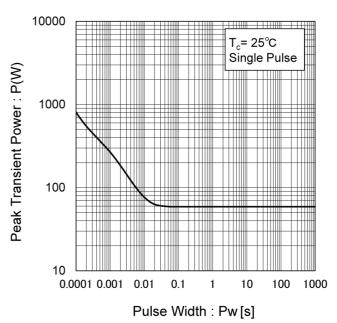


Fig.5 Typical Output Characteristics(I)

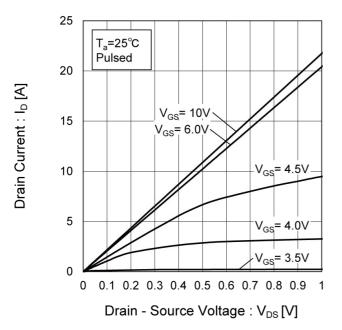


Fig.6 Typical Output Characteristics(II)

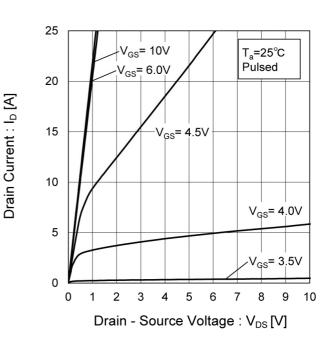


Fig.7 Breakdown Voltage vs.

Junction Temperature

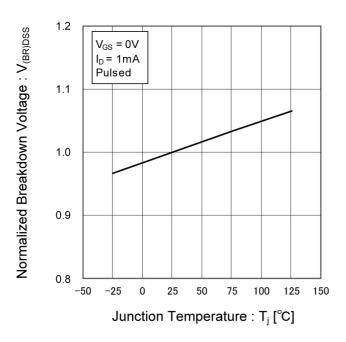


Fig.8 Typical Transfer Characteristics

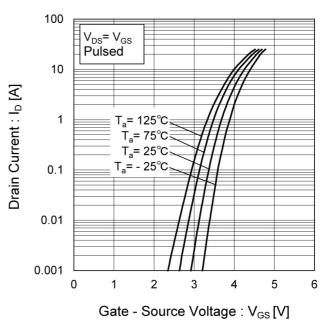


Fig.9 Gate Threshold Voltage vs.
Junction Temperature

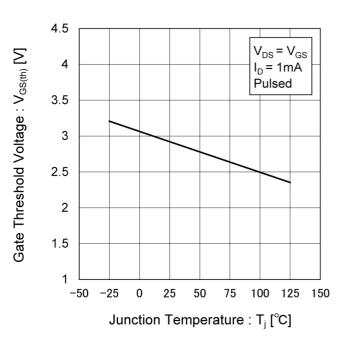


Fig.10 Forward Transfer Admittance vs.
Drain Current

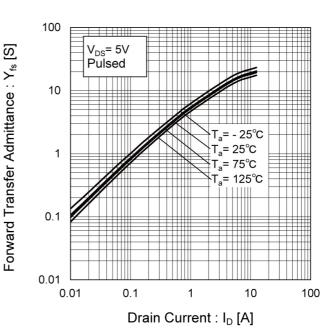


Fig.11 Drain Current Derating Curve

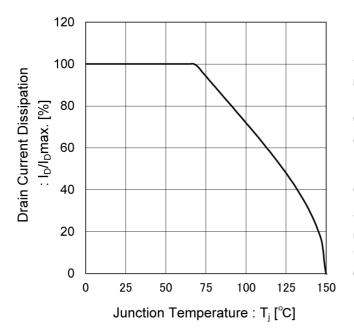


Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

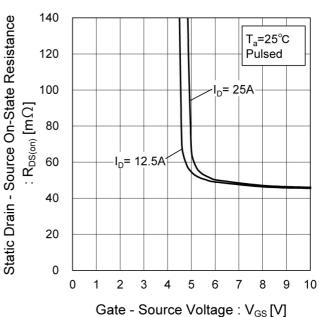


Fig.13 Static Drain - Source On - State
Resistance vs. Junction Temperature

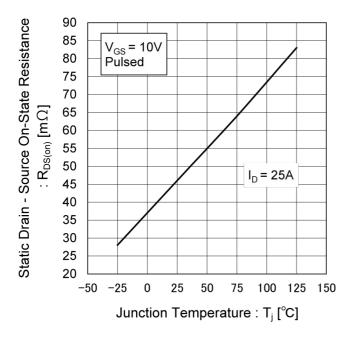


Fig.14 Static Drain - Source On - State
Resistance vs. Drain Current (I)

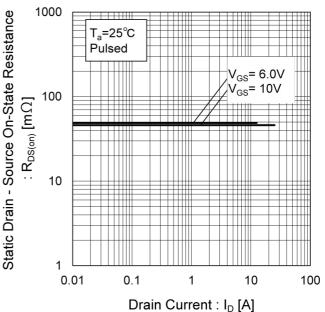


Fig.15 Static Drain - Source On - State Resistance vs. Drain Current (II)

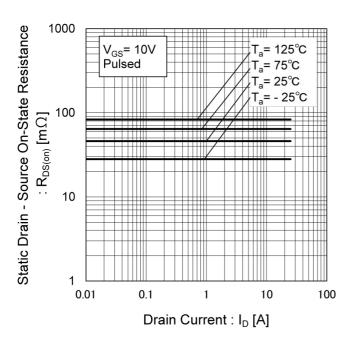


Fig.16 Static Drain - Source On - State Resistance vs. Drain Current (III)

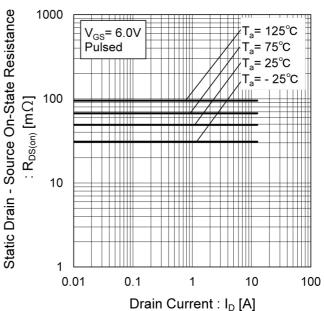


Fig.17 Typical Capacitances vs.

Drain - Source Voltage

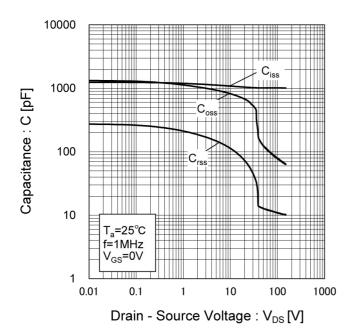


Fig.18 Switching Characteristics

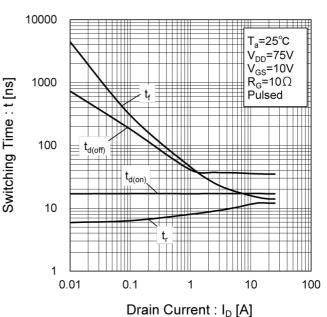


Fig.19 Typical Gate Charge

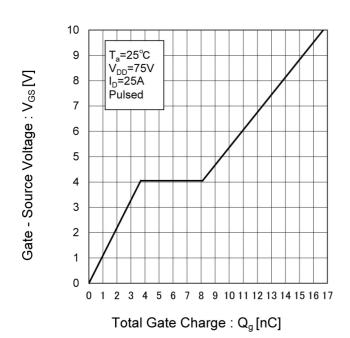
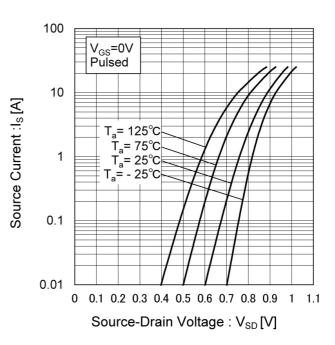


Fig.20 Source Current vs.
Source Drain Voltage



## Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

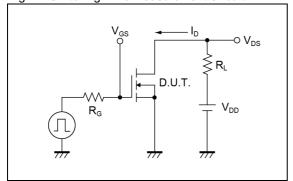


Fig.1-2 Switching Waveforms

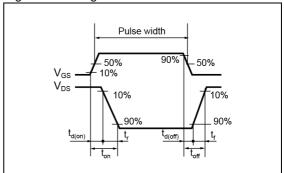


Fig.2-1 Gate Charge Measurement Circuit

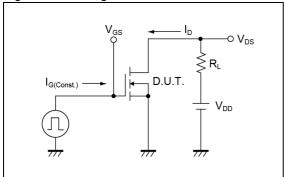


Fig.2-2 Gate Charge Waveform

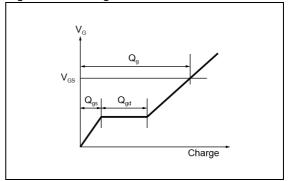


Fig.3-1 Avalanche Measurement Circuit

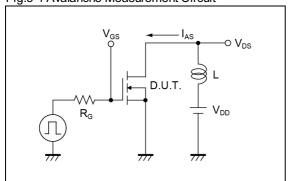
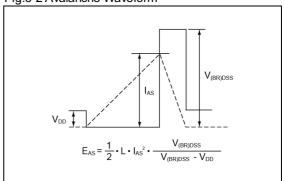


Fig.3-2 Avalanche Waveform

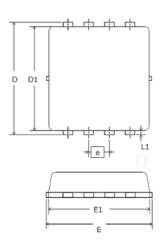


#### Notice

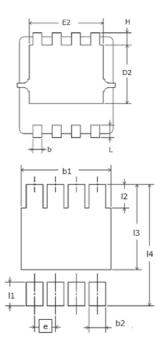
This product might cause chip aging and breakdown under the large electrified environment. Please consider to design ESD protection circuit.

# Dimensions

HSMT8 (TB1) ( 3.3x3.3 )







Refarenced footprint dimensions

DIM -	Milimeters		Inch	nes	
DIM	Min.	Max.	Min.	Max.	
Α	0.70	0.80	0.028	0.031	
b	0.25	0.35	0.010	0.014	
С	0.10	0.25	0.004	0.010	
D	3.25	3.45	0.128	0.136	
D1	3.00	3.20	0.118	0.126	
D2	1.78	1.98	0.070	0.078	
E	3.20	3.40	0.126	0.134	
E1	3.00	3.20	0.118	0.126	
E2	2.39	2.59	0.094	0.102	
е	0.6	55	0.0	26	
Н	0.30	0.50	0.012	0.020	
L	0.30	0.50	0.012	0.020	
L1	0.1	3	0.005		

DIM	Milimeters	Inches
DIM	Nom.	Nom.
- 11	0.70	0.028
12	0.70	0.028
13	2.53	0.100
14	3.60	0.142
b1	0.52	0.020
b2	2.79	0.110

Dimension in mm/inches

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CLASSIV	CLASSⅢ	CLASSⅢ	CLASSⅢ

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  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

#### Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
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#### **Precaution for Electrostatic**

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
  - [a] the Products are exposed to sea winds or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
  may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
  exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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